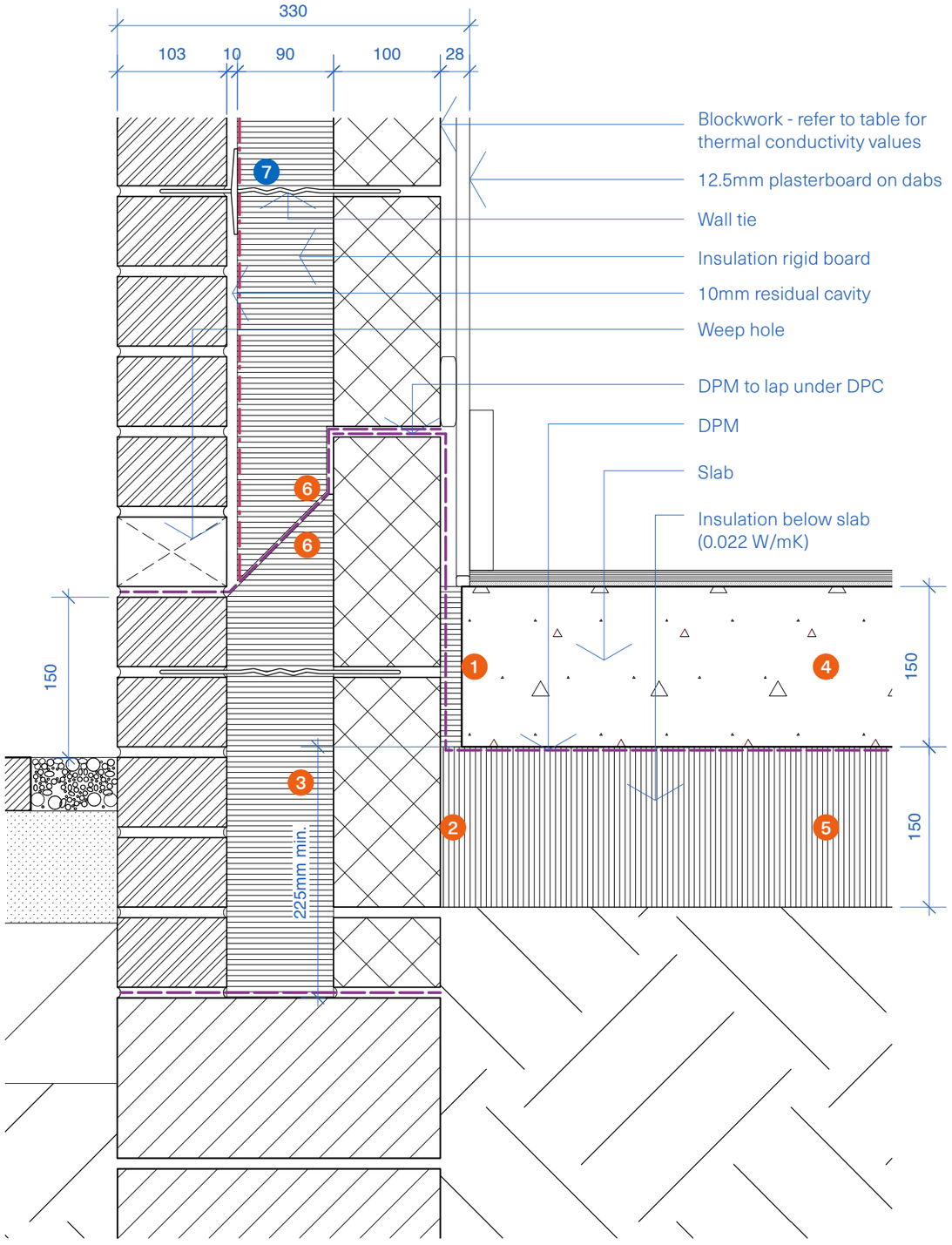
Construction Detail



Calculated Ψ (Psi) value for use in SAP Calculation

	Internal leaf block thermal conductivity (W/mK)					
Insulation thermal conductivity (W/mK)	0.11	0.15	0.19	0.28	0.6	1.33
0.019	**0.050**	**0.060**	**0.068**	**0.066**	**0.102**	**0.165**
0.022	**0.052**	**0.061**	**0.070**	**0.067**	**0.103**	**0.166**

f-values: 0.898 - 0.946 (values above 0.75 indicate low risk of condensation and mould)

Ψ (Psi) value Thermal Compliance Notes

1. Minimum 20mm perimeter insulation with λ≤0.022W/mK.
2. Ensure the floor insulation is tightly butted against the external wall.
3. Continue full fill rigid cavity insulation at least 225mm below slab. Insulation below DPC to provide thermal resistance equal to or better than main wall insulation.
4. 150mm Ground bearing slab.
5. 150mm insulation (0.022 W/mK) below slab.
6. Ensure insulation is cut and fitted around the angle of the cavity tray. Insulation to be secured firmly against the inner leaf of the cavity wall.

Construction Notes

7. Wall tie: No greater than 450mm vertical spacing.
   Only use insulation retaining clips that are compatible with the wall tie.

General Notes

Rigid insulation below DPC to provide structural stability and stop water ingress.